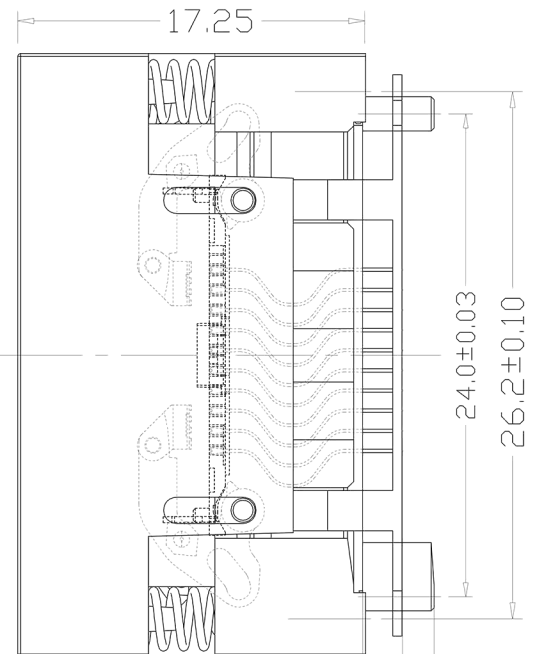
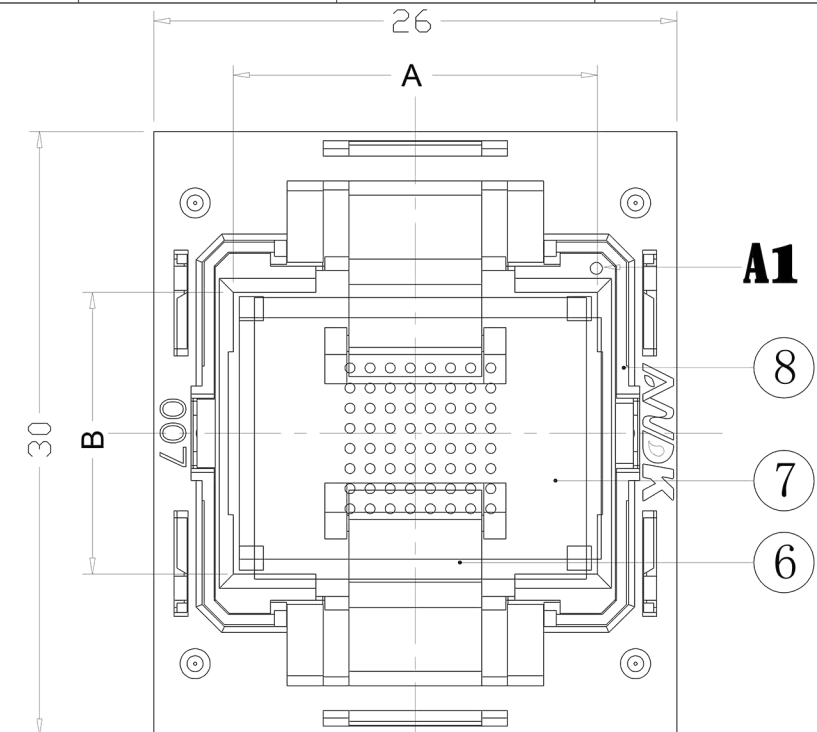
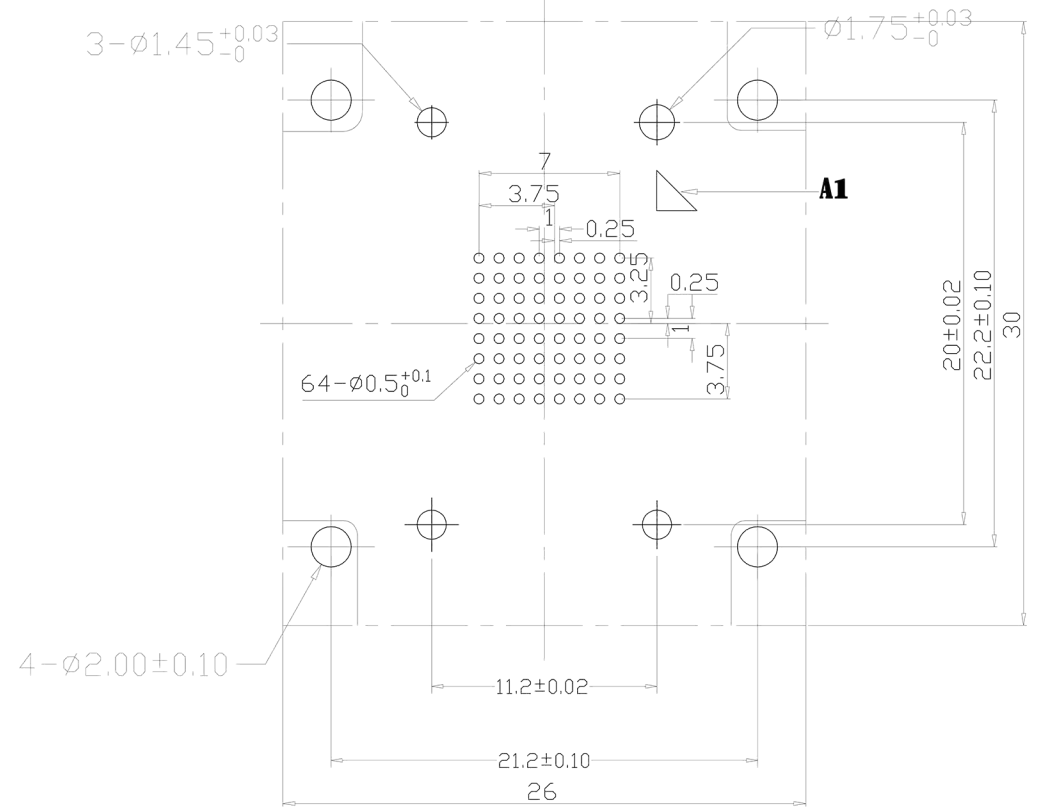


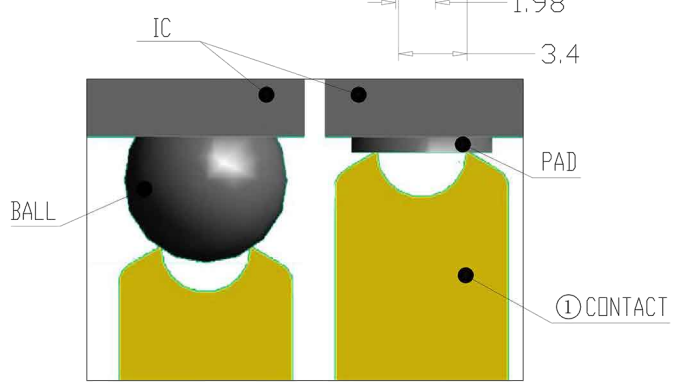
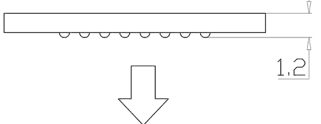
REVISION	DESCRIPTION	CHECK	APP	DATE	REV. NOTICE .NO
△ 1					
△ 2					
△ 3					



**PCB Pattern(TOP View)**

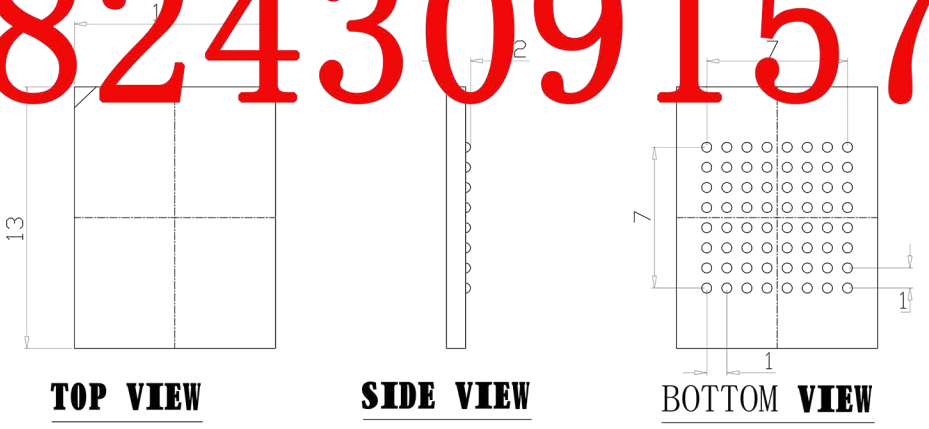
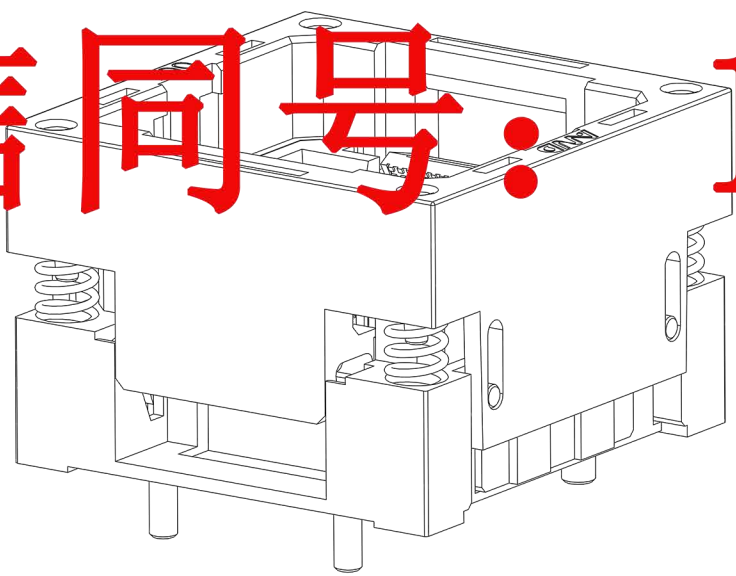
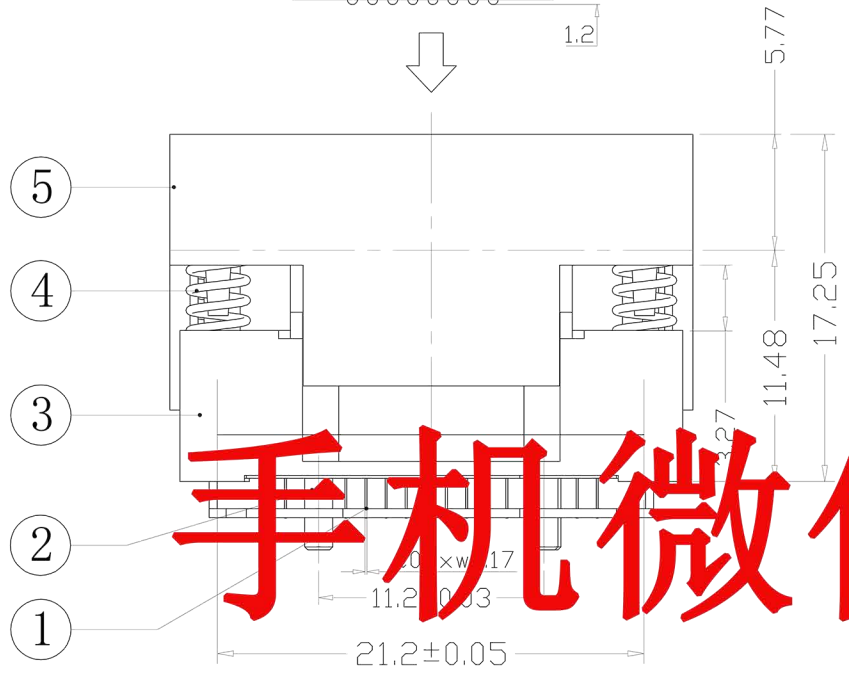


**IC Loading Direction  
(Center In)**



**CONTACT TIP DETAIL**

Applicable IC



**TOP VIEW**

**SIDE VIEW**

**BOTTOM VIEW**

手机微信同号: 18824309157

PERFORMANCE

1. Insulation Resistance: 1000MΩ Min.At DC 500V
2. Dielectric Withstanding Voltage For 1 Minute At AC 700V
3. Contact Resistance 30mΩ MAX. at 10mA and 20mV MAX.(Initial)
4. Current Rating: 1A max.
5. Operation Temperature -65°C ~+175°C
6. Contact Force 3-5g Per Pin (Normal)
7. Testing chips with balls of different size or superficial oxidation,even if no ball

No	Part Number	Name	Material	Q/ty	Note
8	310-048-D105D	IC GUIDE	PEI/PES	2	BLACK
7	310-048-C105D	SLIDER	PEI/PES	1	BLACK
6	310-048-C105D	IC HOLDER	PEI/PES	2	BLACK
5	310-048-B105D	COVER	PEI/PES	1	BLACK
4	20-B-4505B	SPRING	SUS	4	FOR COVER
3	310-048-A105D	BASE	PEI/PES	1	BLACK
2	310-048-F105D	LOCATOR	PEI/PES	3	BLACK
1	04-A-1705	CONTACT	BeCu	64	Au PLATING

PROJECTION		GENERAL TOLERANCES	±0.10	TITLE	BGA64 SOCKET
DIMENSION:	mm	REV	A	CLASS	007-22064E-2101
APP:		SCALE:	1:1	DRW. NO	007-BGA-1.0-64-10X13-B-01
CHECK:		DATE:			
DEGK:	ENG04	DATE:	20121207		